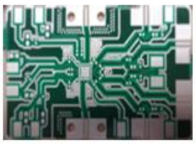
Our Capabilities

Items	*Rigid*	*Flex*	*Rigid-Flex*	*IMS (Metal PCB)*
Layers	1~90L	1~14L	2~36L	1~4L
Max/Min. Board Thickness	10mm	0.075 – 0.4mm	10mm	4mm
Min. Width/Space (Inner Layer)	2.0/2.0 mil	2.0/2.0 mil	2.0/2.0 mil	5.0/5.0 mil
Min. Width/Space (Outer Layer)	2.0/2.0 mil	2.0/2.0 mil	2.0/2.0 mil	5.0/5.0 mil
Solder mask	Green, Red, Blue, Black, White	-	Green, Red, Blue, Black, White	Green, Red, Blue, Black, White
Max. Copper Thickness	12oz	3oz	3oz	6oz
Min. Drill Hole (Mechanical)	≥0.10mm(4mil)	≥0.15mm(6mil)	≥0.10mm(4mil)	≥0.6mm(20mil)
Min. Drill Hole (Laser)	0.075mm	0.05mm	0.075mm	NA
Max. Size (Board size)	1650 x 570 mm	1650 x 570 mm	1250 x 570 mm	1500 x 300 mm
Aspect Ratio	1:50	-	1:14	1:5
Selective area Copper plating	Up to 1.5oz from base copper	-	-	-
Material (FR4)	**IT180A, IT158,** 370HR, S1000-2, S1000 / S1155, R1566W, EM285, TU862HF			
Material (High Speed)	**TU872SLK, EM528,Megtron6,** Megtron4, Megtron7, FR408HR, N4000-13 Series, EM526, EM890K			
Material (High Frequency)	**Ro4003,Ro4350B,** Ro4360G2, Ro4835			
Material (Others)	Polyimide, Tk, LCP, BT,, AL: 1W-8W			
Surface Finish	HASL, ENIG, Immersion Tin, OSP, Immersion Silver, Electroplating Hard Gold/Soft Gold, Gold Finger, Selective OSP, ENEPIG			

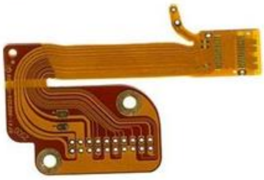
Micro-wave Material Hybrid
Application: Power Amplifier of Communication Base Stations



8L; THK:1.6MM
Application: Industry Control

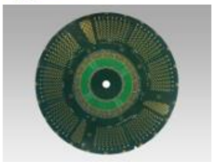
Multilayer, 10L
Application: Medical Control

Double size Flex Board
Application: AIOT

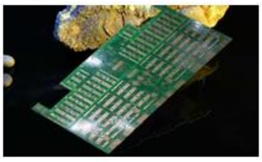


48L 4 Step HDI Board
Application:
Communications satellite

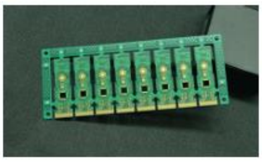
36 layers; Thk: 5.0mm
Application: ICT Test



32-Layer Board
Application: Super Computer



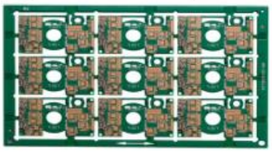
10L HDI Anylayer
Gold Finger Board
Application: Optical



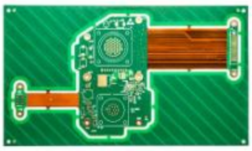
Al-base Board
Application: LED Power

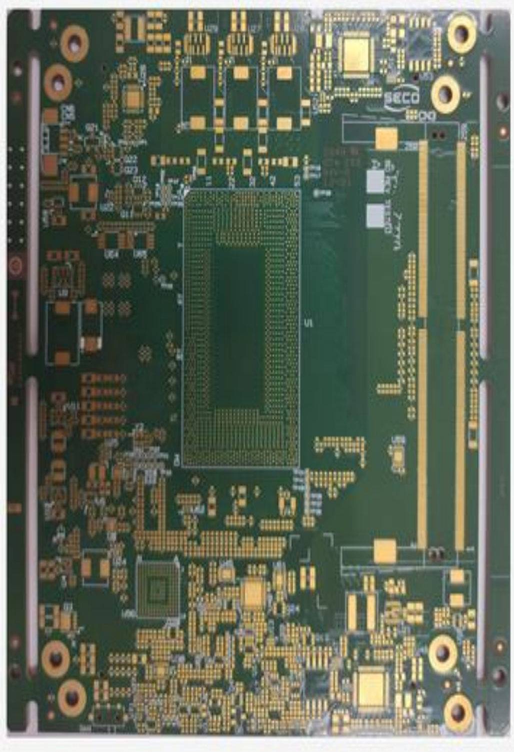
4L HDI Rigid - flex Board
Application: Camera Module

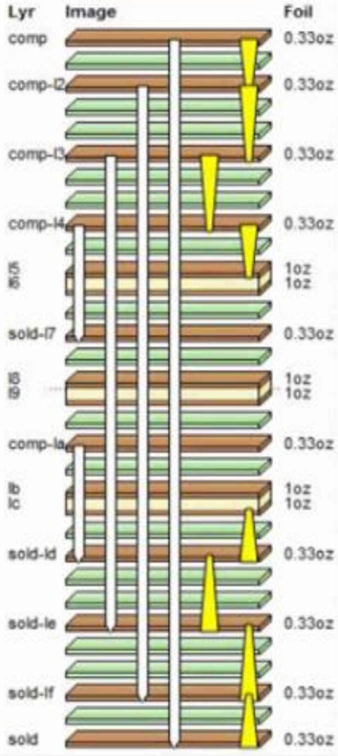
Heavy copper PCB
14L, 3.0mm
Application: Industry control



12-layer Rigid-Flex board
Application: Industry Control







Board Type:Rigid HDI

Application:Industry Computer

Layers:16L

Structure:4+8+4

Material:EM526

Finished THK:2.0MM

Min W/S:3.2/2.8mil

Surface Finish:ENIG

Board Type:Rigid HDI

Application:Industry

Layers:24L

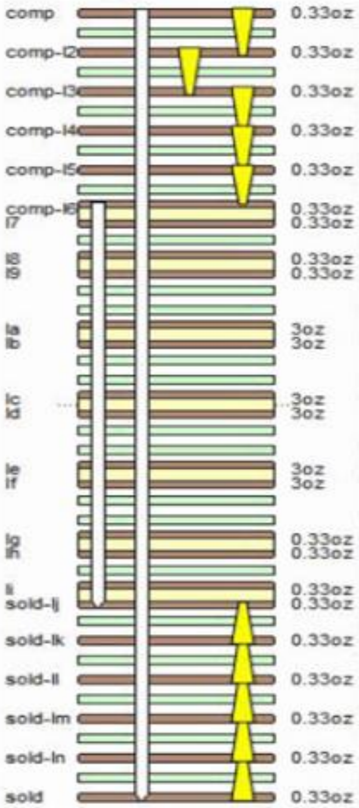
Structure:5+14+5

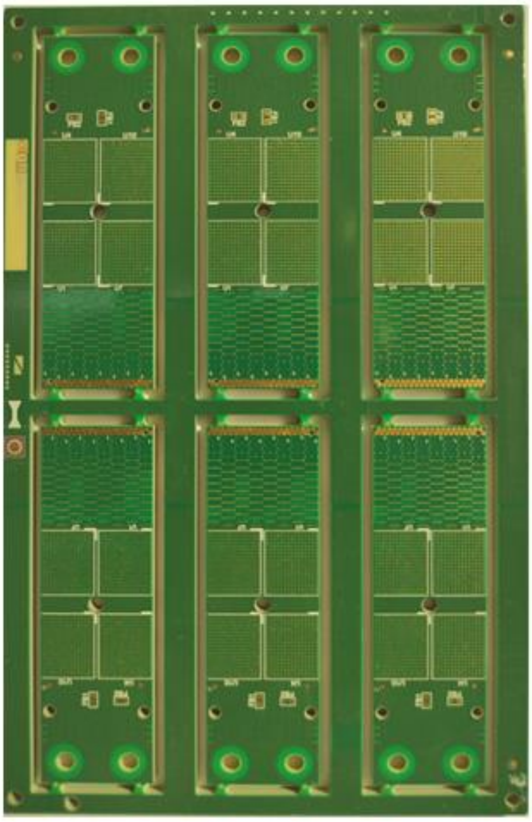
Material:EM370Z

Finished THK:2.95MM

Min W/S:2.5/3.2mil

Surface Finish:ENIG





Board Type:Rigid Anylayer HDI

Application:Communication

Layers:12L

Structure:Anylayer

Material:EM390

Finished THK:1.0MM

Min W/S:2.2/2.0mil

Surface Finish:OSP